

ABSTRACT

There is provided a copper bonding wire that exhibits a favorable bondability even when a scrub at the time of bonding is reduced. The copper bonding wire is characterized in that when a sum of percentages of Cu, Cu₂O, CuO and Cu(OH)₂ on a surface of the wire as measured by X-ray Photoelectron Spectroscopy (XPS) is defined as 100%, Cu[II]/Cu[I] which is a ratio of a total percentage of CuO and Cu(OH)₂ (Cu[II]) corresponding to bivalent Cu to a percentage of Cu₂O (Cu[I]) corresponding to monovalent Cu falls within a range from 0.8 to 12.

[No figure]